

Substitute form 1449A/PTO

Complete if Known

# INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet 1 of 7

Application Number 10/780,529  
 Filing Date February 17, 2004  
 First Named Inventor Jong-Rong Jan  
 Group Art Unit 2818  
 Examiner Name Chuong A. Luu  
 Attorney Docket Number 9180-30

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Date Considered

01/06/2006

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			Group Art Unit	2818
			Examiner Name	Chuong A. Luu
(use as many sheets as necessary)			Attorney Docket Number	9180-30
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			Examiner Name	Chuong A. Luu	
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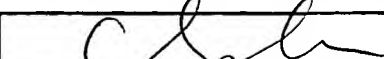
OTHER NON PATENT LITERATURE DOCUMENTS					T
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published			
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Examiner Signature		Date Considered	07/06/2006
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Substitute form 1449A/PTO				<b>Complete if Known</b>	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)				Application Number	10/780,529
				Filing Date	February 17, 2004
				First Named Inventor	Jong-Rong Jan
				Group Art Unit	2818
				Examiner Name	Chuong A. Luu
Sheet	7	of	7	Attorney Docket Number	9180-30

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<i>CA</i>	269.	Zeng et al; <i>Six cases of reliability study of Pb-free solder joints in electronic packaging technology</i> , Reports: A Review Journal; Materials Science and Engineering R 38 (2002) pp 55-105.	

Examiner Signature	<i>CA</i>	Date Considered	01/06/2006
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